



Material Content Data Sheet



Sales Product Name				BSZ100N06LS3 G		Issued		24. January 2018	
MA#				MA001255840					
Package				PG-TSDSON-8-2		Weight*		39.83 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.296	3.25	3.25	32540	32540	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		53		
	non noble metal	zinc	7440-66-6	0.008	0.02		210		
	non noble metal	iron	7439-89-6	0.168	0.42		4210		
wire	non noble metal	copper	7440-50-8	6.808	17.09	17.54	170930	175403	
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	898	898	
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.09		945	
plastics	plastics	epoxy resin	-	1.937	4.86		48646		
	inorganic material	silicondioxide	60676-86-0	16.835	42.30	47.25	422696	472287	
	non noble metal	tin	7440-31-5	0.387	0.97	0.97	9721	9721	
plating	noble metal	silver	7440-22-4	0.963	2.42	2.42	24169	24169	
solder	noble metal	silver	7440-22-4	0.037	0.09		923		
	non noble metal	tin	7440-31-5	0.029	0.07		738		
	non noble metal	lead	7439-92-1	1.404	3.52	3.68	35243	36904	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		108		
	non noble metal	iron	7439-89-6	0.086	0.22		2165		
heat sink CLIP	non noble metal	copper	7440-50-8	3.501	8.79	9.02	87909	90209	
	inorganic material	phosphorus	7723-14-0	0.002	0.00		47		
	non noble metal	zinc	7440-66-6	0.008	0.02		189		
*deviation	non noble metal	iron	7439-89-6	0.151	0.38		3789		
	non noble metal	copper	7440-50-8	6.127	15.38	15.78	153844	157869	
	Sum in total:						100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com